

General Description

The WSF4042 is the highest performance trench N-ch and P-ch MOSFET with extreme high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications. The WSF4042 meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

Features

- Advanced high cell density Trench technology
- Super Low Gate Charge
- Excellent CdV/dt effect decline
- 100% EAS Guaranteed
- Green Device Available

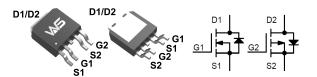
Product Summery

BVDSS	RDSON	ID
40V	14mΩ	20A
-40V	16mΩ	-20A

Applications

- High Frequency Point-of-Load Synchronous Buck Converter for MB/NB/UMPC/VGA
- Networking DC-DC Power System
- CCFL Back-light Inverter

TO-252-4L Pin Configuration



Absolute Maximum Ratings

		Rating			
Symbol	Parameter		N-Ch P-Ch		
V_{DS}	Drain-Source Voltage	40	-40	V	
V_{GS}	Gate-Source Voltage	±20	±20	V	
I _D @T _C =25℃	Continuous Drain Current, V _{GS} @ 10V ¹	20	-20	Α	
I _D @T _C =100℃	Continuous Drain Current, V _{GS} @ 10V ¹	16	-14	А	
I _{DM}	Pulsed Drain Current ²	80	-80	А	
EAS	Single Pulse Avalanche Energy ³	25	25	mJ	
I _{AS}	Avalanche Current	10	-10	Α	
P _D @T _C =25°C	Total Power Dissipation⁴	32.9	32.9	W	
T _{STG}	Storage Temperature Range	-55 to 150	-55 to 150	$^{\circ}$	
TJ	Operating Junction Temperature Range	150	150	$^{\circ}\! \mathbb{C}$	

Thermal Data

Symbol	Parameter	Тур.	Max.	Unit
$R_{ heta JA}$	Thermal Resistance Junction-Ambient ¹		60	°C/W
$R_{ heta JC}$	Thermal Resistance Junction-Case ¹		3.8	°C/W



N-Ch and P-Channel MOSFET

N-Channel Electrical Characteristics (T_J=25 [™]C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V _{GS} =0V , I _D =250uA	40			V
$\triangle BV_{DSS}/\triangle T_{J}$	BVDSS Temperature Coefficient	Reference to 25℃, I _D =1mA		0.034		V/°C
В	Static Drain-Source On-Resistance ²	V _{GS} =10V , I _D =10A		14	21	mΩ
R _{DS(ON)}	Static Dialii-Source Off-Resistance	V _{GS} =4.5V , I _D =5A		18	25	11122
V _{GS(th)}	Gate Threshold Voltage	\/ -\/ -250\	1.5	2.0	2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=250uA$		-4.56		mV/℃
	Drain Source Leakage Current	V_{DS} =32V , V_{GS} =0V , T_J =25 $^{\circ}$ C			1	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =32V , V _{GS} =0V , T _J =55℃			5	uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20V$, V_{DS} = $0V$			±100	nA
gfs	Forward Transconductance	V _{DS} =5V , I _D =12A		8		S
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		2.6	5.2	Ω
Q_{g}	Total Gate Charge (4.5V)			7.5		
Q_gs	Gate-Source Charge	V _{DS} =20V , V _{GS} =4.5V , I _D =12A		3.24		nC
Q _{gd}	Gate-Drain Charge			2.75		
T _{d(on)}	Turn-On Delay Time			7.8		
Tr	Rise Time	V_{DD} =20V , V_{GS} =10V , R_{G} =3.3 Ω		6.9		200
T _{d(off)}	Turn-Off Delay Time	I _D =1A		22.4		ns
T _f	Fall Time			4.8		
Ciss	Input Capacitance	V _{DS} =15V , V _{GS} =0V , f=1MHz		815		
C _{oss}	Output Capacitance			95		pF
C _{rss}	Reverse Transfer Capacitance			60		

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
Is	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			10	Α
I _{SM}	Pulsed Source Current ^{2,6}				30	Α
V_{SD}	Diode Forward Voltage ²	V_{GS} =0V , I_{S} =1A , T_{J} =25 $^{\circ}$ C			1.2	V

Note

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =25V, V_{GS} =10V, L=0.1mH, I_{AS} =17.8A
- 4.The power dissipation is limited by 150 ℃ junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.



P-Channel Electrical Characteristics (T_J=25 °C, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
BV _{DSS}	Drain-Source Breakdown Voltage	V_{GS} =0 V , I_D =-250 u A	-40			V
$\triangle BV_{DSS}/\triangle T_{J}$	BV _{DSS} Temperature Coefficient	Reference to 25°C , I _D =-1mA		-0.012		V/°C
D	2	V _{GS} =-10V , I _D =-8A		16	20	m0
R _{DS(ON)}	Static Drain-Source On-Resistance ²	V _{GS} =-4.5V , I _D =-4A		20	24	mΩ
V _{GS(th)}	Gate Threshold Voltage	V -V 1 - 2500A	-1.5	-2.0	-2.5	V
$\triangle V_{GS(th)}$	V _{GS(th)} Temperature Coefficient	$V_{GS}=V_{DS}$, $I_D=-250uA$		4.32		mV/℃
-	Drain Source Leakage Current	V _{DS} =-32V , V _{GS} =0V , T _J =25°C			1	
I _{DSS}	Drain-Source Leakage Current	V _{DS} =-32V , V _{GS} =0V , T _J =55°C			5	- uA
I _{GSS}	Gate-Source Leakage Current	V_{GS} = $\pm 20 V$, V_{DS} = $0 V$			±100	nA
gfs	Forward Transconductance	V_{DS} =-5 V , I_{D} =-8 A		12.6		S
R_g	Gate Resistance	V _{DS} =0V , V _{GS} =0V , f=1MHz		13	16	Ω
Q_g	Total Gate Charge (-4.5V)			7.5		
Q_gs	Gate-Source Charge	V _{DS} =-20V , V _{GS} =-4.5V , I _D =-12A		2.4		nC
Q_gd	Gate-Drain Charge			3.5		
T _{d(on)}	Turn-On Delay Time			8.7		
T _r	Rise Time	V_{DD} =-15V , V_{GS} =-10V , R_{G} =3.3 Ω ,		7		
T _{d(off)}	Turn-Off Delay Time	I _D =-1A		31		ns
T _f	Fall Time			17		
C _{iss}	Input Capacitance	V _{DS} =-15V , V _{GS} =0V , f=1MHz		668		
Coss	Output Capacitance			98		pF
C _{rss}	Reverse Transfer Capacitance			72		

Diode Characteristics

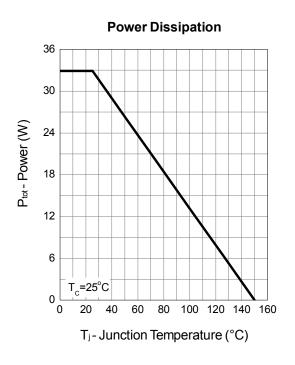
Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
I _S	Continuous Source Current ^{1,6}	V _G =V _D =0V , Force Current			-10	Α
I _{SM}	Pulsed Source Current ^{2,6}				-30	Α
V_{SD}	Diode Forward Voltage ²	V _{GS} =0V , I _S =-1A , T _J =25℃			-1.2	V

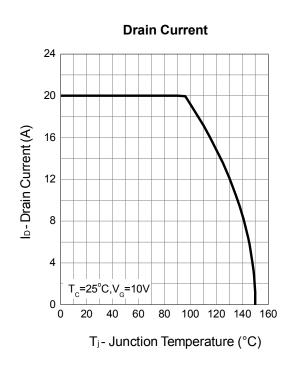
Note

- 1.The data tested by surface mounted on a 1 inch² FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width \leq 300us , duty cycle \leq 2%
- 3. The EAS data shows Max. rating . The test condition is V_{DD} =-25V, V_{GS} =-10V, L=0.1mH, I_{AS} =-27.2A
- 4. The power dissipation is limited by 150 ℃ junction temperature
- 5. The Min. value is 100% EAS tested guarantee.
- 6. The data is theoretically the same as I_D and I_{DM} , in real applications, should be limited by total power dissipation.

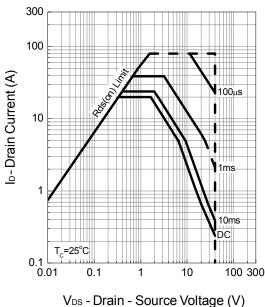


N Channel Typical Operating Characteristics

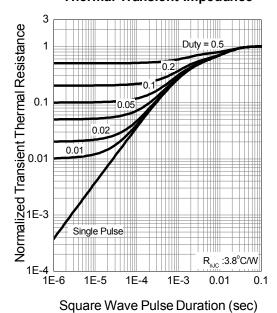




Safe Operation Area

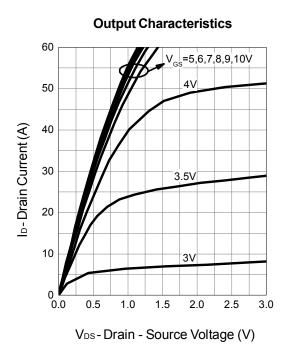


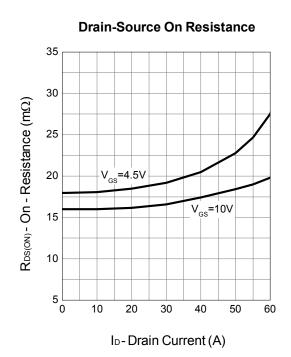
Thermal Transient Impedance

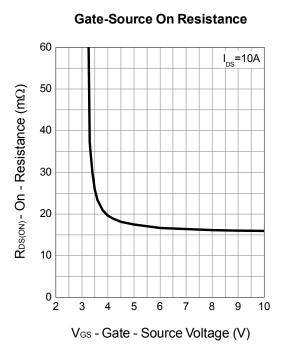


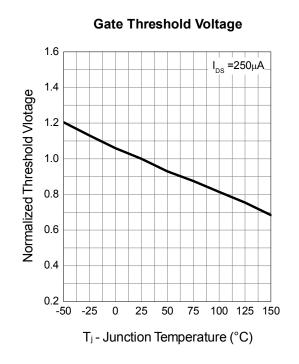


N Channel Typical Operating Characteristics (Cont.)





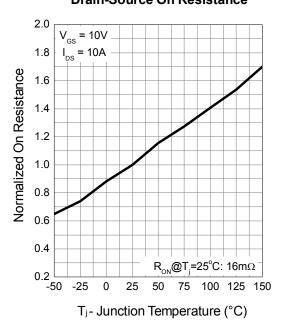




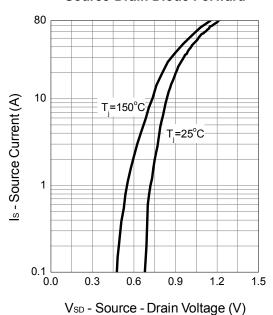


N Channel Typical Operating Characteristics (Cont.)

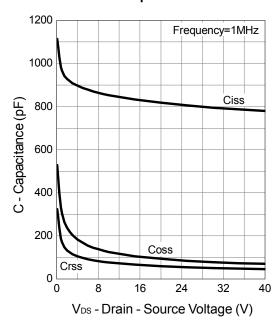
Drain-Source On Resistance



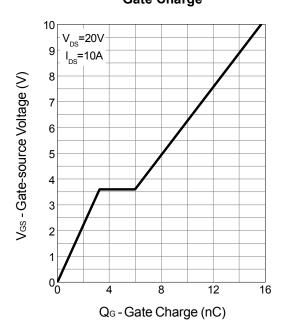
Source-Drain Diode Forward



Capacitance

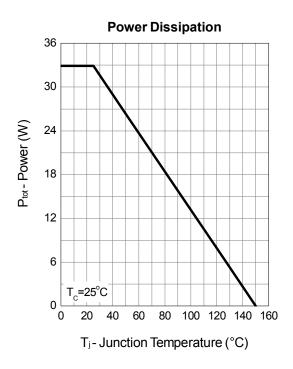


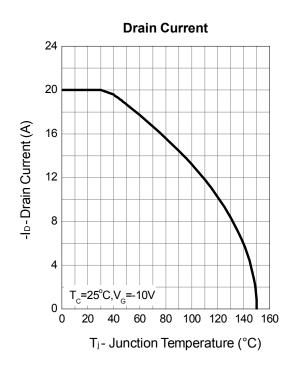
Gate Charge

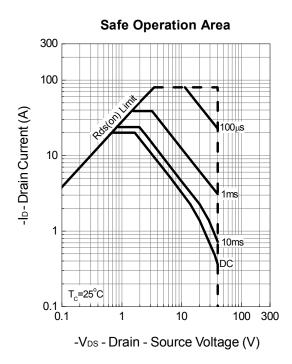


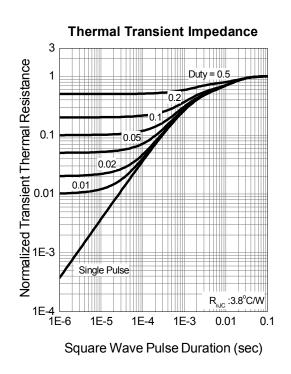


P Channel Typical Operating Characteristics



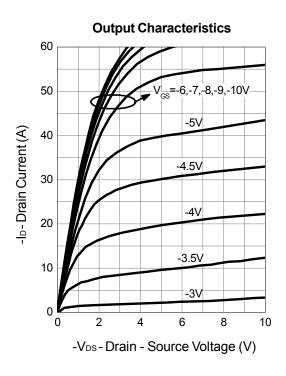


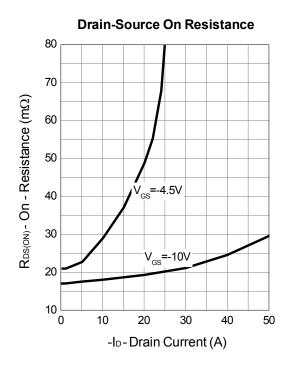


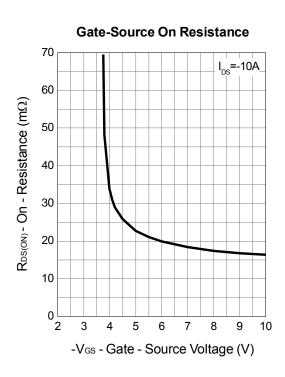


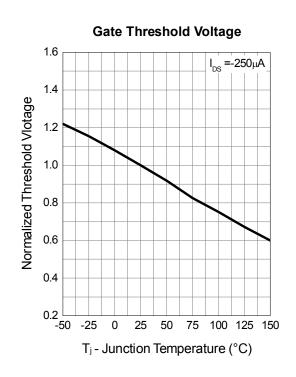


P Channel Typical Operating Characteristics (Cont.)



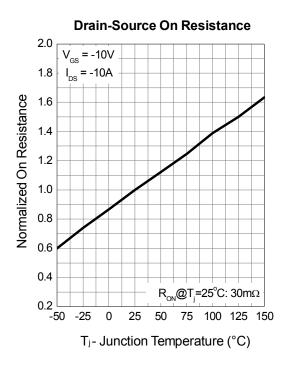


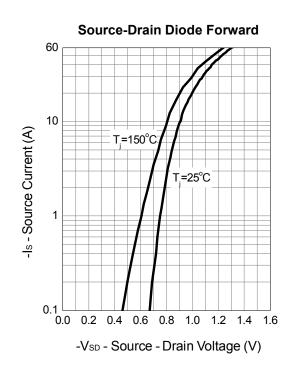


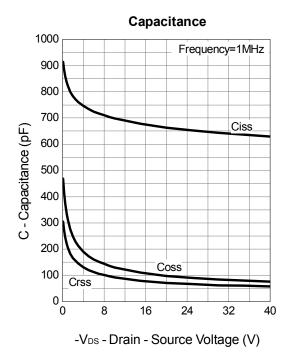


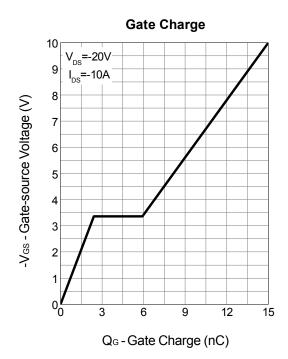


P Channel Typical Operating Characteristics (Cont.)











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